

OCT 17 2005

Reply Under 37 CFR 1.116  
Expedited Procedure  
Art Unit 2825

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: HAMASAKI

Serial No.: 10/814,180

Filed: 4/1/2004

Title: METHOD OF RESIN-SEALING A  
SEMICONDUCTOR DEVICE, AND  
FORMING DIE FOR RESIN SEALING  
THE SEMICONDUCTOR DEVICE

Atty. Dkt.: 01-615

Art Unit: 2825

Examiner: MALSAWMA

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: October 17, 2005

## CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the USPTO (Fax. No. 571-273-8300) on this date: 17 October 2005

Typed Name: Robert L. Scott, II

Signature: AMENDMENT UNDER 37 CFR 1.116

Sir:

In response to the office action mailed May 16, 2005, the time for response to which, since falling on Sunday, October 16, 2005, is automatically extended to today, Monday, October 17, 2005, please amend the application as follows:

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of this paper.

Remarks begin on page 3 of this paper.